

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chia-Hung Hsu	04/09/2011
Ching-San Lin	04/07/2011
Chin-Yung Chen	04/07/2011
RECEIVING PARTY DATA	
Name:	Raydium Semiconductor Corporation
Street Address:	Hsinichu Science Park
Internal Address:	2F, No. 23, Li-hsin Road
City:	Hsinchu 300
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13089480
CORRESPONDENCE DATA	
Fax Number: (732)530-9808 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 732-530-9404 Email: adevesty@pattersonsheridan.com Correspondent Name: Patterson & Sheridan, LLP Address Line 1: 595 Shrewsbury Avenue Address Line 2: Suite 100 Address Line 4: Shrewsbury, NEW JERSEY 07702	
ATTORNEY DOCKET NUMBER:	FORM/0028
NAME OF SUBMITTER:	Keith Taboada
Total Attachments: 2 source=FORM_0028_EASSIGN_4_11#page1.tif source=FORM_0028_EASSIGN_4_11#page2.tif	

OP \$40.00 13089480

501505623

PATENT
REEL: 026151 FRAME: 0085

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	Chia-Hung Hsu 3F., No.17, Fude 1st Rd., Xizhi Dist., New Taipei City 221, Taiwan (R.O.C.)
2)	Ching-San Lin No.43, Ln. 1137, Zhongzheng Rd., Wufeng Township, Taichung County 413, Taiwan (R.O.C.)
3)	Chia-Yung Chen No.2, Aly. 8, Ln. 22, Renhe 9th St., Daxi Township, Taoyuan County 335, Taiwan (R.O.C.)

(hereinafter referred to as Assignors), have invented a certain invention entitled:

Die Structure and Die Connecting Method

Enclosed herewith or for which application for Letters Patent in the United States was filed on:
 (a) April 19, 2011, under Serial No. 13/089,480.

WHEREAS, Raydium Semiconductor Corporation, a corporation of Taiwan, Republic of China, having a place of business at 2F, No.23, Li-Hsin Rd., Hsinchu Science Park, Hsinchu 300, Taiwan, R.O.C. (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a conventional, division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or

(Y10005; 10P081005USA)
1793595

1 of 2

desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, conventional, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefore and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

5. In the event that the filing date and/or Application No. of said Invention are not entered above at the time Assignors execute this document, and if such information is deemed necessary, Assignors hereby authorize and request the attorney/agent(s) of **Patterson & Sheridan, LLP**, 595 Shrewsbury Avenue, Suite 100, Shrewsbury, NJ 07702 to insert above the filing date and/or Application No. of said application.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below:

1)	<u>2011.4.7</u> (DATE)	<u>Chia-Hung Hsu</u> Chia-Hung Hsu
2)	<u>2011.04.07</u> (DATE)	<u>Ching-San Lin</u> Ching-San Lin
3)	<u>2011.04.07</u> (DATE)	<u>Chin-Yung Chen</u> Chin-Yung Chen